

Claims

[c1] What is claimed is:

1. A wafer holder for semiconductor manufacturing equipment, the wafer holder having a surface for carrying wafers and comprising:
a high-frequency RF power-generating electrode circuit round in form, built into the wafer holder, the electrode circuit diameter being 90% or more of the diameter of wafers that the wafer holder carries.

[c2] 2. A wafer holder for semiconductor manufacturing equipment, the wafer holder having a surface for carrying wafers and comprising:
a high-frequency RF power-generating electrode circuit, built into the wafer holder, the distance between the electrode circuit peripherally and the wafer holder peripherally being longer than the distance separating the electrode circuit from the wafer-carrying surface.

[c3] 3. A wafer holder as set forth in claim 1, wherein the distance between the periphery of the high-frequency RF power-generating electrode circuit built into the wafer holder and the periphery of the wafer holder is longer than the distance separating said electrode circuit from

the wafer-carrying surface.

[c4] 4. Semiconductor manufacturing equipment wherein the wafer holder set forth in claim 2 is installed.

[c5] 5. Semiconductor manufacturing equipment wherein the wafer holder set forth in claim 3 is installed.